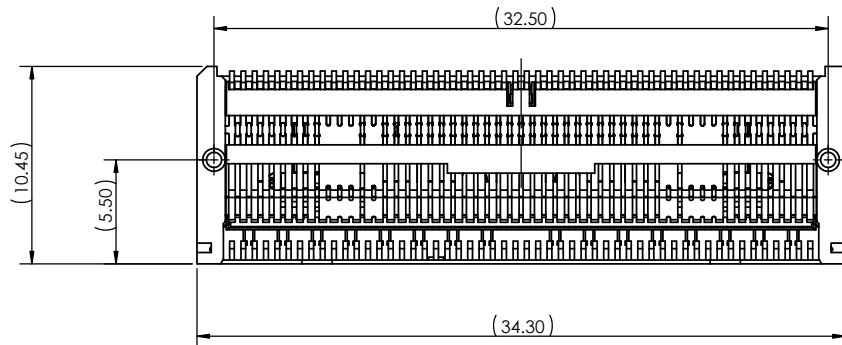
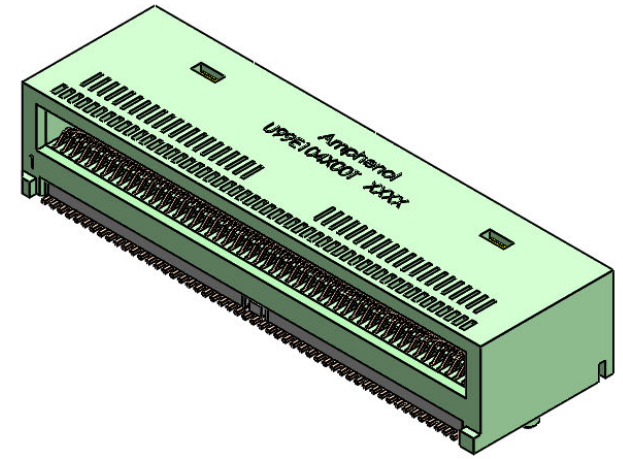
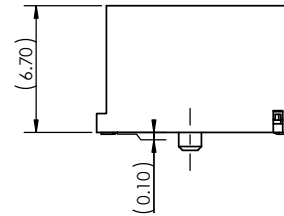
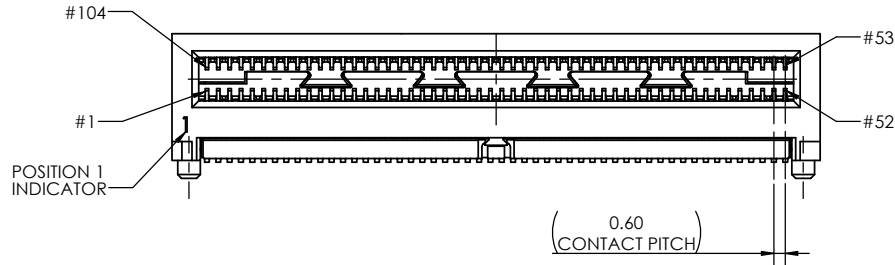
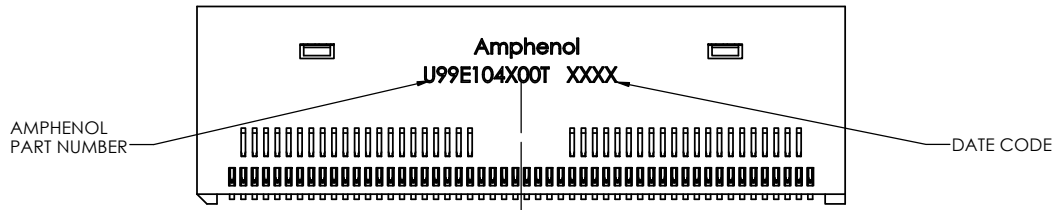


REVISIONS				
REV	ECN	DESCRIPTION	DATE	APP'D
A	---	DRAWN	JUN04/18	AZ
B	---	RECEPTACLE VIEWS UPDATED	APR20/21	CM



U99 - E104 - X X X X

OPTIONS

00T = STANDARD CONSTRUCTION WITH TAPE & REEL PACKAGING

CONTACT PLATING OPTION

2 = 30µin (0.76µm) MINIMUM OF GOLD ON MATING END WITH 100µin (2.54µm) MINIMUM OF MATTE TIN ON SOLDER TERMINATION, 50µin (1.27µm) MIN. NICKEL UNDER-PLATE ALL OVER.

3 = 15µin (0.38µm) MINIMUM OF GOLD ON MATING END WITH 100µin (2.54µm) MINIMUM OF MATTE TIN ON SOLDER TERMINATION, 50µin (1.27µm) MIN. NICKEL UNDER-PLATE ALL OVER.

4 = 24µin (0.61µm) MINIMUM GXT ON MATING END WITH 100µin (2.54µm) MINIMUM OF MATTE TIN ON SOLDER TERMINATION, 50µin (1.27µm) MIN. NICKEL UNDER-PLATE ALL OVER.

MODEL

E = 56Gbps PAM4/ACO RECEPTACLE CONNECTOR

NOTES:

1. MATERIAL:

HOUSING: HIGH TEMPERATURE THERMOPLASTIC, GLASS FILLED, UL94V-0
CONTACTS: COPPER ALLOY
RESONANCE DAMPENING FEATURE: COPPER ALLOY

2. RoHS COMPLIANT.

3. COMPLIANT WITH MSA SPECIFICATION CFP2 BASELINE DRAWING REV1L.



UNLESS SPECIFIED OTHERWISE	DRAWN	C. MICHLIK	JUN04/18
PRIMARY UNITS MILLIMETRES	CHECKED	C. MICHLIK	JUN04/18
SECONDARY INCHES	M.E. APP'D		
REFERENCE IN PARENTHESES	Q.A. APP'D		
GENERAL TOLERANCES	DWG APP'D	A. ZEREBILOV	JUN05/18
1 DECIMAL PLACE ±0.2	ENG. REL. NO.	---	
2 DECIMAL PLACES ±0.10	REF.		
3 DECIMAL PLACES ±0.050	THIRD ANGLE PROJECTION		
ANGULAR DEGREES ±2°	DO NOT SCALE DRAWING		

Amphenol High Speed Interconnects
A Division of Amphenol Corp. www.amphenolcanada.com

CFP2 56Gbps PAM4/ACO 104 POSITION RECEPTACLE CONNECTOR

DWG. NO.	REV
P-U99-E104-XXXX	B
CODE ID NO. 03554	DWG SIZE: C
SCALE: 5:1	SHEET 1 OF 2

